

FAST CMOS OCTAL LATCHED TRANSCEIVER

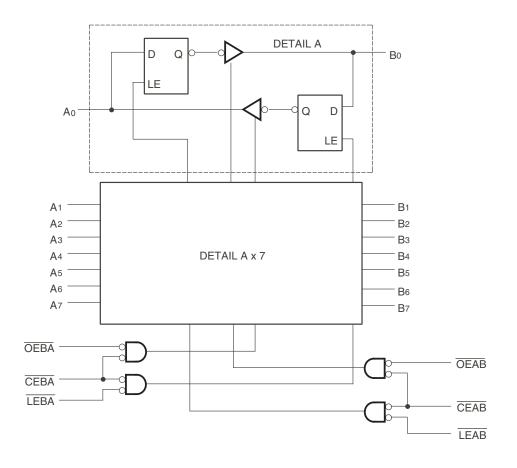
FEATURES:

- A and C grades
- Low input and output leakage ≤1µA (max.)
- CMOS power levels
- True TTL input and output compatibility:
 - -VOH = 3.3V (typ.)
 - -VOL = 0.3V(typ.)
- High Drive outputs (-15mA IOH, 64mA IOL)
- Meets or exceeds JEDEC standard 18 specifications
- Power off disable outputs permit "live insertion"
- Available in SOIC and QSOP packages

DESCRIPTION:

The FCT543T is a non-inverting octal transceiver built using an advanced dual metal CMOS technology. This device contains two sets of eight D-type latches with separate input and output controls for each set. For data flow from A to B, for example, the A-to-B Enable (CEAB) input must be low in order to enter data from Ao–A7 or to take data from Bo–B7, as indicated in the Function Table. With CEAB low, a low signal on the A-to-B Latch Enable (LEAB) input makes the A-to-B latches transparent; a subsequent low-to-high transition of the LEAB signal puts the A latches in the storage mode and their outputs no longer change with the A inputs. With CEAB and OEAB both low, the 3-state B output buffers are active and reflect the data present at the output of the A latches. Control of data from B to A is similar, but uses the CEBA, LEBA and OEAA inputs.

FUNCTIONAL BLOCK DIAGRAM



INDUSTRIAL TEMPERATURE RANGE



PINCONFIGURATION



TOP VIEW

Package Type	Package Code	Order Code
QSOP	PCG24	QG
SOIC	PSG24	SOG

INDUSTRIALTEMPERATURERANGE

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	–0.5 to +7	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
Tstg	Storage Temperature	-65 to +150	°C
Ιουτ	DC Output Current	-60 to +120	mA

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability. No terminal voltage may exceed Vcc by +0.5V unless otherwise noted.

2. Inputs and Vcc terminals only.

3. Output and I/O terminals only.

CAPACITANCE (TA = +25°C, F = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	6	10	pF
Соит	Output Capacitance	Vout = 0V	8	12	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PINDESCRIPTION

Pin Names	Description
ŌĒĀB	A-to-B Output Enable Input (Active LOW)
ŌĒBĀ	B-to-A Output Enable Input (Active LOW)
CEAB	A-to-B Enable Input (Active LOW)
CEBA	B-to-A Enable Input (Active LOW)
LEAB	A-to-B Latch Enable Input (Active LOW)
LEBA	B-to-A Latch Enable Input (Active LOW)
A0-A7	A-to-B Data Inputs or B-to-A 3-State Outputs
B0-B7	B-to-A Data Inputs or A-to-B 3-State Outputs

FUNCTION TABLE^(1, 2)

For A-to-B (Symmetric with B-to-A)

	Inputs		Latch Status	Output Buffers
CEAB	LEAB	OEAB	A-to-B	B0-B7
Н	Х	Х	Storing	High Z
Х	Н	Х	Storing	Х
Х	Х	Н	Х	High Z
L	L	L	Transparent	Current A Inputs
L	Н	L	Storing	Previous* A Inputs

NOTES:

1. * Before LEAB LOW-to-HIGH Transition

- H = HIGH Voltage Level
- L = LOW Voltage Level
- X = Don't Care

 A-to-B data flow shown; B-to-A flow control is the same, except using CEBA, LEBA and OEBA.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40° C to $+85^{\circ}$ C, VCC = $5.0V \pm 5\%$

Symbol	Parameter	Test	t Conditions ⁽¹⁾	Min.	Тур. ⁽²⁾	Max.	Unit
Vih	Input HIGH Level	Guaranteed Logic HIGH L	evel	2	—	_	V
Vil	Input LOW Level	Guaranteed Logic LOW Le	evel	-	—	0.8	V
Ін	Input HIGH Current ⁽⁴⁾	Vcc = Max.	VI = 2.7V	_	_	±1	μA
lil	Input LOW Current ⁽⁴⁾	Vcc = Max.	VI = 0.5V	_	_	±1	μA
Іогн	High Impedance Output Current	Vcc = Max	Vo = 2.7V	_	_	±1	μA
Iozl	(3-State output pins) ⁽⁴⁾		Vo = 0.5V	-	—	±1	
lı	Input HIGH Current ⁽⁴⁾	VCC = Max., VI = VCC (M	ax.)	_	_	±1	μA
Vik	Clamp Diode Voltage	VCC = Min, IIN = -18mA	VCC = Min, IIN = -18mA		-0.7	-1.2	V
Vн	Input Hysteresis	_		-	200	_	mV
lcc	Quiescent Power Supply Current	VCC = Max., VIN = GND C	or Vcc	-	0.01	1	mA

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Тур. ⁽²⁾	Max.	Unit
Vон	Output HIGH Voltage	Vcc = Min	Iон = –8mA	2.4	3.3	—	V
		VIN = VIH or VIL	Iон = –15mA	2	3		
Vol	Output LOW Voltage	Vcc = Min	IOL = 64mA	_	0.3	0.55	V
		VIN = VIH or VIL					
los	Short Circuit Current	Vcc = Max., Vo = GND ⁽³⁾		-60	-120	-225	mA
Ioff	Input/Output Power Off Leakage ⁽⁵⁾	VCC = 0V, VIN or VO \leq 4.5V		_	_	±1	μA

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at Vcc = 5.0V, +25°C ambient.

3. Not more than one output should be tested at one time. Duration of the test should not exceed one second.

4. The test limit for this parameter is $\pm 5\mu A$ at TA = -55°C.

5. This parameter is guaranteed but not tested.



POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditi	ons ⁽¹⁾	Min.	Тур. ⁽²⁾	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	Vcc = Max. VIN = 3.4V ⁽³⁾		-	0.5	2	mA
ICCD	Dynamic Power Supply Current ⁽⁴⁾	Vcc = Max., Outputs Open CEAB and OEAB = GND CEBA = Vcc One Input Toggling 50% Duty Cycle	Vin = Vcc Vin = GND	_	0.15	0.25	mA/ MHz
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max., Outputs Open fcp = 10MHz (LEAB) 50% Duty Cycle CEAB and OEAB = GND	Vin = Vcc Vin = GND	-	1.5	3.5	mA
		CEBA = Vcc One Bit Toggling at fi = 5MHz 50% duty cycle	Vin = 3.4V Vin = GND	_	2	5.5	
		Vcc = Max., Outputs Open fcp = 10MHz (LEAB) 50% Duty Cycle CEAB and OEAB = GND	VIN = VCC VIN = GND	—	3.8	7.3(5)	mA
		CEBA= VccEight Bits Togglingat fi = 2.5MHz50% duty cycle	VIN = 3.4V VIN = GND	_	6	16.3 ⁽⁵⁾	

NOTES:

1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at Vcc = 5.0V, +25°C ambient.

3. Per TTL driven input; (VIN = 3.4V). All other inputs at Vcc or GND.

4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.

5. Values for these conditions are examples of Δ Icc formula. These limits are guaranteed but not tested.

6. IC = IQUIESCENT + INPUTS + IDYNAMIC

IC = ICC + Δ ICC DHNT + ICCD (fCP/2+ fiNi)

Icc = Quiescent Current

 ΔIcc = Power Supply Current for a TTL High Input (VIN = 3.4V)

- DH = Duty Cycle for TTL Inputs High
- NT = Number of TTL Inputs at DH

ICCD = Dynamic Current caused by an Input Transition Pair (HLH or LHL)

fcp = Clock Frequency for Register Devices (Zero for Non-Register Devices)

fi = Output Frequency

Ni = Number of Outputs at fi

All currents are in milliamps and all frequencies are in megahertz.

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SWITCHING CHARACTERISTICS OVER OPERATING RANGE

			74FCT	543AT	74FC1	543CT	
Symbol	Parameter	Condition ⁽¹⁾	Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	Unit
t PLH	Propagation Delay	CL = 50pF	1.5	6.5	1.5	5.3	ns
t PHL	TransparantMode	$RL = 500\Omega$					
	Ax to Bx or Bx to Ax						
t PLH	Propagation Delay]	1.5	8	1.5	7	ns
t PHL	LEBA to Ax, LEAB to Bx						
tpzh	Output Enable Time]	1.5	9	1.5	8	ns
tPZL	OEBA or OEAB to Ax or Bx						
	$\overline{\text{CEBA}}$ or $\overline{\text{CEAB}}$ to Ax or Bx						
tphz	Output Disable Time		1.5	7.5	1.5	6.5	ns
tPLZ	OEBA or OEAB to Ax or Bx						
	\overline{CEBA} or \overline{CEAB} to Ax or Bx						
tsu	Set-up Time, HIGH or LOW		2	—	2	—	ns
	Ax or Bx to $\overline{\text{LEBA}}$ or $\overline{\text{LEAB}}$						
ħ	Hold Time, HIGH or LOW]	2	_	2	_	ns
	Ax or Bx to $\overline{\text{LEBA}}$ or $\overline{\text{LEAB}}$						
tw	LEBA or LEAB Pulse Width LOW		5	_	5	—	ns

NOTES:

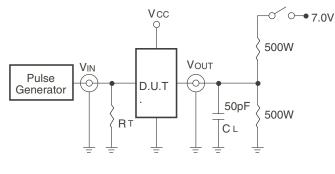
1. See test circuit and waveforms.

2. Minimum limits are guaranteed but not tested.

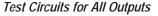
74FCT543AT/CT FASTCMOSOCTALLATCHEDTRANSCEIVER

INDUSTRIAL TEMPERATURE RANGE

TEST CIRCUITS AND WAVEFORMS



Octal Link



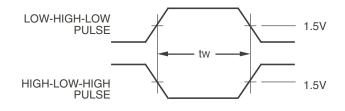


Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

DEFINITIONS:

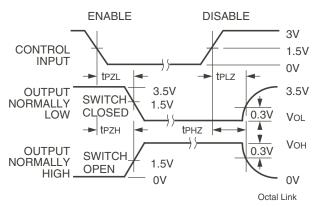
CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to Zout of the Pulse Generator.



Pulse Width

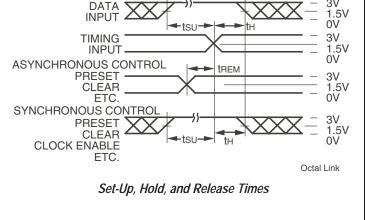
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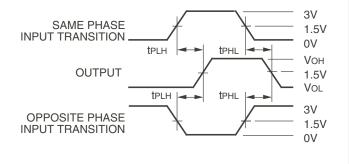


Enable and Disable Times

NOTES:

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tF \leq 2.5ns; tR \leq 2.5ns.



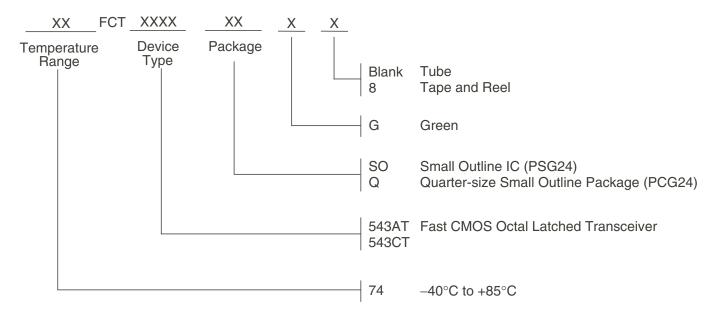


Propagation Delay

Octal Link



ORDERING INFORMATION



Orderable Part Information

Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
Α	74FCT543ATQG	PCG24	QSOP	I
	74FCT543ATQG8	PCG24	QSOP	I
	74FCT543ATSOG	PSG24	SOIC	I
	74FCT543ATSOG8	PSG24	SOIC	I
С	74FCT543CTQG	PCG24	QSOP	I
	74FCT543CTQG8	PCG24	QSOP	I
	74FCT543CTSOG	PSG24	SOIC	I
	74FCT543CTSOG8	PSG24	SOIC	I

Datasheet Document History

10/10/2009Pg.6Updated the ordering information by removing the "IDT" notation and non RoHS part.05/16/2018Pgs.2, 7Added table under pin configuration diagram with detailed package information. Updated the ordering information
diagram adding Tube, Tape and Reel. Added new table of orderable part information.05/10/2019Pg. 7Updated ordering information diagram.

02/11/2020 Pgs. 1-8 Rebranded as Renesas datasheet.



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